20th IEEE European Test Symposium
Cluj-Napoca, Romania
May 25 – 29, 2015
http://www.ieee-ets.org

Information for Prospective Corporate Supporters

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2015 European Test Symposium Corporate Support Opportunity “At a Glance”

- ETS is the annual premier European event totally devoted to test and test-synthesis of micro-electronic circuits and systems, attracting around 200 industrial and academic professionals from around the world.
- ETS 2015 will be held in Cluj-Napoca, Romania, on May 25–29, 2015.
- Your company is invited to support ETS'15 at Bronze (€1500), Silver (€2500), Gold (€5000) or Platinum (€8000) level.
- The money will be used solely to cover the costs associated with ETS, thereby attracting yet more attendees.
- In return company will get many benefits depending on the support level; examples are (a) Sponsor’s name and logo on ETS web page, posters, program booklet, projection screen, and the proceedings that will be distributed to the participants, (b) Advertising space in the program booklet, (c) Advertisement e-mail to registered participant, (d) Getting priority in the selection process for the Vendor Sessions, (e) Getting priority in slot assignment for Table-Top Demo Sessions, etc.
- Since its start, ETS has been sponsored by dozens companies; examples are: Advantest, Alter, ARM, Cadence Design Systems, Elsys, GöPEL electronic GmbH, Honeywell, Infineon Technologies, Intel, JTAG technologies, Mentor Graphics, NXP Semiconductors, OptimalTest, Pintail Technologies, Preciosa, Q-Star Test, Qualcomm, Qualtera, Spea, STC, STMicroelectronics, Synopsys, SynTest, Teradyne, TestAdvantage, TestInsight, Verigy, VSystems, etc.

About ETS’15

As you probably know, the IEEE European Test Symposium (ETS) is the largest European event completely devoted to testing micro-electronic circuits and systems. ETS is organized annually in a different European country. In 2015, ETS will be held in Cluj-Napoca, Romania, and will take place May 25-29.

The ETS program comprises plenary keynotes, parallel paper sessions, vendor sessions, poster sessions, panel sessions, spring school, and fringe workshops. ETS is also renowned for its excellent Social Event and informal atmosphere, providing many opportunities for networking. ETS is annually attended by many design, design-for-test, and test professionals from companies and academia.

To find out more about ETS’15, visit http://www.ets15.ro.

Corporate Support ETS’15

Since its start, ETS have been supported by large number of word-wide companies and SMEs. The donation is solely used to cover costs associated with ETS and make the event accessible to more attendees. In return ETS gives the Sponsor different benefit depending on the support grade as explained in Section “ETS’15 Support Grades”. These include:

- Sponsor’s name and logo on ETS web page, posters, program booklet, projection screen, and the proceedings that will be distributed to the participants.
- Advertising space in the program booklet,
- Advertisement e-mail to registered participant,
- Display of company logos during session intervals,
- Opportunity to provide company hand-out material,
- Getting priority in the selection process for the Vendor Sessions,
- Getting priority in slot assignment for Table-Top Demo Sessions,
- Etc.

We therefore would like to invite your company to become a corporate supporter of ETS’15 and contribute to a successful event! Your presence at the symposium will give you an excellent opportunity to network with established and new design, test and reliability engineers.
ETS'15 Corporate Support Grades

ETS has defined four different support grades, each with different support amounts and different benefit options.

1. **Bronze**: At least €1500
   - Supporter's name and logo will appear in the symposium's web page, the symposium posters, and the printed programs that will be distributed to the participants.
   - *Half-page* advertising space in the program booklet for the event. The Advance Program will be available as a downloadable PDF document before the event, and the Final Program will be a hard-copy booklet handed out to all registered attendees.
   - Priority in slot assignment for the Vendor Sessions.
   - Constant exposure of company logo in a repeating presentation loop before, in-between, and after sessions.
   - The supporter will be allowed to provide branded give-away items for inclusion in the symposium registration bag.

2. **Silver**: At least €2500
   - As per Bronze Level, plus:
     - *Full-page* advertising space in the program booklet.
     - The supporter's name and logo will appear in the proceedings of the symposium.
     - The supporter's name and logo will appear on the symposium's registration bag.
     - Opportunity to send out one advertisement e-mail to registered symposium participants prior to the symposium.

3. **Gold**: At least €5000
   - As per Silver Level, plus:
     - A special area and/or Table Top Demo at the symposium site will be assigned to the supporter as its own demonstration area (posters, leaflets, recruitment material, and other advertisement material). This could be a table (provided by ETS) or a booth (supplied by the corporate supporter).
     - Opportunity to send out two advertisement e-mails to registered symposium participants prior to the symposium.

4. **Platinum**: At least €8000
   - This is a Main Corporate Supporter. As per Gold Level, plus:
     - Guaranteed slot assignment in the Vendor Sessions.
     - The support money will be used primarily for the Social Event of the workshop, which will be announced “to be offered by the Main Supporter(s)”.
     - Additional publicity paths can be arranged as requested by the supporter.

**Vendor Session Presentations**

ETS offers commercial vendors the opportunity to give technical presentations in a track parallel to the technical paper sessions. These presentations will be listed in the symposium program along with the technical sessions, and are targeted to the ETS technical audience. The Vendor Sessions differ from standard ETS presentations in that company names, logos, and product names may be mentioned explicitly. Content could include product descriptions, case studies, best practices, and testimonials.

Presentation opportunities of 30-minutes duration are available: proposal selection is based the technical contact and relevance to the ETS audience and topics. To find out more about the Vendor Sessions, visit the ETS web site at and follow the link to Vendor Sessions, Call for Submissions, or send an e-mail requesting more information. Please note that ETS guarantee a presentation slot in the Vendor Session only for Platinum Corporate Sponsors. Nevertheless, we will do our utmost to accommodate your request taking into consideration your Corporate Support Grade and the available time slots at the symposium.

**Demo Area/ Table Top Demo**

ETS symposium offers a demo area and/or Table-Top Demo. You can make use of the opportunity to present/demonstrate e.g., posters, leaflets, recruitment material, advertisement material, technical descriptions, case studies, best practices, user testimonials of products or solutions, etc. These presentations will be listed in the workshop program booklet along with the regular paper sessions, and should be targeted to the Symposium technical audience. Demo Area/ Table-Top Demo differ from other symposium presentations in that a company name, logo, and product name may be mentioned explicitly.

**Further information**

If your company is interested to become a corporate supporter and take advantage of opportunities describe above or if you need any additional information, please contact the ETS Industrial Relations Chair, Said Hamdioui S.Hamdioui@tudelft.nl.
Affiliations of Past ETS Attendees

Advantest (Europe)
Advantest America
Agilent Technologies
Altter Technology Group Spain
AMD Corporation
Analog Devices
Aptina Imaging
ARM Ltd
ASI-Centrum s.r.o.
Atmel Norway & Rousset
Atrenta Inc
Auburn University
Azoteq
Bahcesehir University
Blue Pearl Software
Bordeaux 1 University
Brno University of Technology
Brown University
Cadence Design Systems
Catholic University - PUCRS
CEA Grenoble - LETI/DCIS/SCME
CEA LIST
Chiba University
Chinese Academy of Sciences
Chinese University of Hong Kong
Cisco Systems Inc
CNM - IMSE
Credence Systems (UK) Ltd
Credence Systems Corporation
CTU Prague
DAFCA
DeFacTo Technologies
Delft University of Technology
DMOS GmbH
Duke University
Electronic Systems & Software IET
ELES Semiconductor Equipment S.p.A.
ELMOS Semiconductor
EPSRC
Ericsson
ETH Zurich
European Patent Office
European University of Brest
Federal University of RGS - UFRGS
FEI STU
Focused Solutions Alliance
Fraunhofer IIS / EAS
Freescale Semiconductor
Georgia Institute of Technology
Graz University of Technology
Grenoble INP
Hiroshima City University
Huawei Technology Co Ltd
IBM
IHP GmbH
IM2NP
IMAG
IMEC
IMP GmbH
IMSE-CNMI
INAOE
Indian Institute of Science Bangalore
Indian Institute of Technology Kharagpur
Infineon Technologies AG
Institute for Semiconductor Technology
Institute of Control Sciences RAM
Intel Corporation
Ippon Innovation
IROC Technologies
IST/INESC.ID
IXL Laboratory
JHU/Applied Physics Laboratory
Jozef Stefan Institute
KTH/IECS
Kuwait University
Kyushu Institute of Technology
Lancaster University
LCIS/INPG
Linköping University
LIRMM
LogicVision
Loughborough University
LSI Logic Corporation
LTX Corporation
MAGMA Design Corporation
McMaster University
Mechatronys S.r.l.
National Tsing-Hua University Taiwan
National University of Defense Technology
NEC Labs
Newcastle University
Nokia Oyj
Norwegian Univ. of Science and Technology
Novas Software
NUDT
NXP Semiconductors
Optimal Test
Oxford University
Philips Electronics
Philips Research
Pintail Technologies
Politecnico di Milano
Politecnico di Torino
Pontificia Universidad Catolica del Peru
Poznan University of Technology
PSA Peugeot Citroen
Purdue University
Qimonda AG
Q-Star Test
Qualcomm
Renesas Electronics Europe GmbH
Robert Bosch GmbH
Russia Academy of Science
Samsung Electronics
Schlumberger SRPC
SEMICON Europe
Semtech Ltd
SFPEngineering
Sharif University of Technology, Iran
Silesian University of Technology
Slovak Academy of Science
Slovak University of Technology
SPEA S.p.A
STMicroelectronics
Synopsys Inc.
Tallinn University of Technology
Technical University of Catalonia
Technical University of Cluj-Napoca
Technical University of Liberec
Technical University of Vienna
Technical University of Prague
Teradyne, Inc.
Test Advantage Inc
TestInsight Ltd.
Texas Instruments
Thales - Aerospace Division
Thomas Bata University
TIMA
TNO
Tokyo Metropolitan University
Tsinghua University
TU Berlin
UC San Diego
UFRGS – Univ. Federal do Rio Grande Sul
Universidade de Vigo
Universidade Federal de Pelotas
Université de les Illes Balears
Universitat Politècnica de Catalunya
Universität Freiburg
Universität Paderborn
University Carlos III de Madrid
University College Cork
University of Alabama
University of Algarve
University of Bologna
University of Bremen
University of Bristol
University of Cantabria
University of Edinburgh
University of Erlanger-Nürnberg
University of Freiburg
University of Hannover
University of Ioannina
University of Iowa
University of Limerick
University of Madrid
University of Manchester
University of Massachusetts Lowell
University of Michigan
University of Newcastle Upon Tyne
University of Oulu
University of Passau
University of Patras, Greece
University of Pireaus
University of Potsdam
University of Pretoria
University of Rome
University of Seville
University of Southampton
University of Stuttgart
University of Technology Poznan
University of Tehran
University of Texas
University of Texas at Austin
University of Tokushima
University of Tokyo
University of Twente
University of Verona
University of Waterloo, Canada
University of Western Britain
University of Wisconsin – Madison
UPMC / LIP6 / ASIM
UUTIA AV CR
Verified Systems International GmbH
Vergiy
Virage Logic
Waseda University
Yogitech SpA